

256K x 16 Static RAM

Features

- · High speed
 - $-t_{AA} = 15 \text{ ns}$
- · Low active power
 - —1430 mW (max.)
- Low CMOS standby power (L version)
 - 2.75 mW (max.)
- 2.0V Data Retention (400 μW at 2.0V retention)
- Automatic power-down when deselected
- TTL-compatible inputs and outputs
- Easy memory expansion with $\overline{\text{CE}}$ and $\overline{\text{OE}}$ features

Functional Description

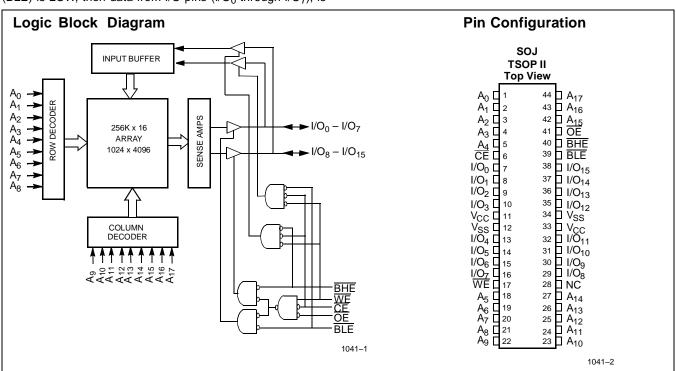
The CY7C1041 is a high-performance CMOS static RAM organized as 262,144 words by 16 bits.

Writing to the device is accomplished by taking Chip Enable (\overline{CE}) and Write Enable (\overline{WE}) inputs LOW. If Byte Low Enable (BLE) is LOW, then data from I/O pins (I/O₀ through I/O₇), is written into the location specified on the address pins (A₀ through A₁₇). If Byte High Enable (BHE) is LOW, then data from I/O pins (I/O₈ through I/O₁₅) is written into the location specified on the address pins (A_0) through A_{17}).

Reading from the device is accomplished by taking Chip Enable (CE) and Output Enable (OE) LOW while forcing the Write Enable (WE) HIGH. If Byte Low Enable (BLE) is LOW, then data from the memory location specified by the address pins will appear on I/O₀ to I/O₇. If Byte High Enable (BHE) is LOW, then data from memory will appear on I/O₈ to I/O₁₅. See the truth table at the back of this data sheet for a complete description of read and write modes.

The input/output pins (I/O₀ through I/O₁₅) are placed in a high-impedance state when the device is deselected (CE HIGH), the outputs are disabled (OE HIGH), the BHE and BLE are disabled (BHE, BLE HIGH), or during a write operation (CE LOW, and $\overline{\text{WE}}$ LOW).

The CY7C1041 is available in a standard 44-pin 400-mil-wide body width SOJ and 44-pin TSOP II package with center power and ground (revolutionary) pinout.



Selection Guide

		7C1041-12	7C1041-15	7C1041-17	7C1041-20	7C1041-25
Maximum Access Time (ns)	12	15	17	20	25	
Maximum Operating Current (mA)	280	260	250	230	220	
Maximum CMOS Standby Current	Com'l	3	3	3	3	3
(mA)	Com'l L	0.5	0.5	0.5	0.5	0.5
	Ind'l	6	6	6	6	6

Shaded areas contain preliminary information.



Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.) Storage Temperature-65°C to +150°C Ambient Temperature with Power Applied–55°C to +125°C Supply Voltage on $\rm V_{CC}$ to Relative $\rm GND^{[1]}$ –0.5V to +7.0V DC Voltage Applied to Outputs in High Z State^[1]......-0.5V to V_{CC} + 0.5V

DC Input Voltage ^[1]	–0.5V to V _{CC} + 0.5V
Current into Outputs (LOW)	20 mA

Operating Range

Range	Ambient Temperature ^[2]	v _{cc}
Commercial	0°C to +70°C	5V ± 0.5
Industrial	–40°C to +85°C	

Electrical Characteristics Over the Operating Range

				7C1041-12		7C10)41-15	7C10)41-17	
Parameter	Description	Test Condit	Test Conditions		Max.	Min.	Max.	Min.	Max.	Unit
V _{OH}	Output HIGH Voltage	$V_{CC} = Min., I_{OH} = -4$.0 mA	2.4		2.4		2.4		V
V _{OL}	Output LOW Voltage	$V_{CC} = Min., I_{OL} = 8.0$) mA		0.4		0.4		0.4	V
V _{IH}	Input HIGH Voltage			2.2	V _{CC} + 0.5	2.2	V _{CC} + 0.5	2.2	V _{CC} + 0.5	V
V _{IL}	Input LOW Voltage[1]			-0.5	0.8	-0.5	0.8	-0.5	0.8	V
I _{IX}	Input Load Current	$GND \le V_1 \le V_{CC}$	$GND \le V_I \le V_{CC}$			-1	+1	-1	+1	μА
I _{OZ}	Output Leakage Current	$\begin{array}{l} \text{GND} \leq \text{V}_{\text{OUT}} \leq \text{V}_{\text{CC}}, \\ \text{Output Disabled} \end{array}$		-1	+1	-1	+1	-1	+1	μА
I _{CC}	V _{CC} Operating Supply Current	$V_{CC} = Max.,$ $f = f_{MAX} = 1/t_{RC}$			280		260		250	mA
I _{SB1}	Automatic CE Power-Down Current —TTL Inputs	$\begin{aligned} &\text{Max. V}_{\text{CC}}, \overline{\text{CE}} \geq \text{V}_{\text{IH}} \\ &\text{V}_{\text{IN}} \geq \text{V}_{\text{IH}} \text{ or} \\ &\text{V}_{\text{IN}} \leq \text{V}_{\text{IL}}, \ f = f_{\text{MAX}} \end{aligned}$			40		40		40	mA
I _{SB2}	Automatic CE	Max. V _{CC} ,	Com'l		3		3		3	mA
	Power-Down Current —CMOS Inputs	$\overline{\text{CE}} \ge V_{\text{CC}} - 0.3V,$ $V_{\text{IN}} \ge V_{\text{CC}} - 0.3V,$	Com'l L		0.5		0.5		0.5	mA
		or $V_{IN} \le 0.3V$, $f = 0$	Ind'I		6		6		6	mA

Shaded areas contain preliminary information.

V_{IL} (min.) = -2.0V for pulse durations of less than 20 ns.
 T_A is the case temperature.



Electrical Characteristics Over the Operating Range (continued)

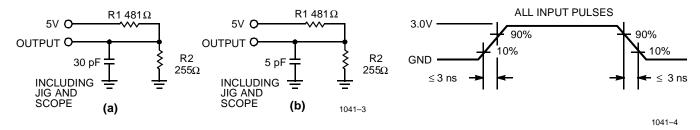
		Test Condition	ons	7C1041-20		7C	1041-25	
Parameter	Description			Min.	Max.	Min.	Max.	Unit
V _{OH}	Output HIGH Voltage	$V_{CC} = Min., I_{OH} = -4.0$) mA	2.4		2.4		V
V _{OL}	Output LOW Voltage	$V_{CC} = Min., I_{OL} = 8.0$	mA		0.4		0.4	V
V _{IH}	Input HIGH Voltage					2.2	V _{CC} + 0.5	V
V _{IL}	Input LOW Voltage ^[1]			-0.5	0.8	-0.5	0.8	V
I _{IX}	Input Load Current	$GND \leq V_I \leq V_{CC}$		-1	+1	-1	+1	μΑ
I _{OZ}	Output Leakage Current	$\begin{array}{l} {\sf GND} \leq {\sf V}_{\sf OUT} \leq {\sf V}_{\sf CC}, \\ {\sf Output \ Disabled} \end{array}$		-1	+1	-1	+1	μΑ
I _{CC}	V _{CC} Operating Supply Current	$V_{CC} = Max.,$ $f = f_{MAX} = 1/t_{RC}$			230		220	mA
I _{SB1}	Automatic CE Power-Down Current —TTL Inputs	Max. V_{CC} , $\overline{CE} \ge V_{IH}$ $V_{IN} \ge V_{IH}$ or $V_{IN} \le V_{IL}$, $f = f_{MAX}$			40		40	mA
I _{SB2}	Automatic CE	Max. V _{CC} ,	Com'l		3		3	mA
	Power-Down Current —CMOS Inputs	$\overline{CE} \ge V_{CC} - 0.3V$, $V_{IN} \ge V_{CC} - 0.3V$,	Com'l L		0.5		0.5	mA
	Owice inputs	or $V_{IN} \le 0.3V$, $f = 0$	Ind'l		6		6	mA

Capacitance^[3]

Parameter	Description	Test Conditions	Max.	Unit
C _{IN}	Input Capacitance	$T_A = 25^{\circ}C$, f = 1 MHz,	8	pF
C _{OUT}	I/O Capacitance	$V_{CC} = 5.0V$	8	pF

Note:

AC Test Loads and Waveforms



Equivalent to: THÉVENIN EQUIVALENT

^{3.} Tested initially and after any design or process changes that may affect these parameters.



$\textbf{Switching Characteristics}^{[4]} \ \text{Over the Operating Range}$

		7C10)41-12	7C10	41-15	7C10	41-17	
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Unit
READ CYC	LE	<u> </u>			•		•	
t _{RC}	Read Cycle Time	12		15		17		ns
t _{AA}	Address to Data Valid		12		15		17	ns
t _{OHA}	Data Hold from Address Change	3		3		3		ns
t _{ACE}	CE LOW to Data Valid		12		15		17	ns
t _{DOE}	OE LOW to Data Valid		6		7		7	ns
t _{LZOE}	OE LOW to Low Z	0		0		0		ns
t _{HZOE}	OE HIGH to High Z ^[5, 6]		6		7		7	ns
t _{LZCE}	CE LOW to Low Z ^[6]	3		3		3		ns
t _{HZCE}	CE HIGH to High Z ^[5, 6]		6		7		7	ns
t _{PU}	CE LOW to Power-Up	0		0		0		ns
t _{PD}	CE HIGH to Power-Down		12		15		17	ns
t _{DBE}	Byte Enable to Data Valid		6		7		7	ns
t _{LZBE}	Byte Enable to Low Z	0		0		0		ns
t _{HZBE}	Byte Disable to High Z		6		7		7	ns
WRITE CYC	CLE ^[7, 8]	•	•	•	•	•	•	
t _{WC}	Write Cycle Time	12		15		17		ns
t _{SCE}	CE LOW to Write End	10		12		14		ns
t _{AW}	Address Set-Up to Write End	10		12		14		ns
t _{HA}	Address Hold from Write End	0		0		0		ns
t _{SA}	Address Set-Up to Write Start	0		0		0		ns
t _{PWE}	WE Pulse Width	10		12		14		ns
t _{SD}	Data Set-Up to Write End	7		8		8		ns
t _{HD}	Data Hold from Write End	0		0		0		ns
t _{LZWE}	WE HIGH to Low Z ^[6]	3		3		3		ns
t _{HZWE}	WE LOW to High Z ^[5, 6]		6		7		7	ns
t _{BW}	Byte Enable to End of Write	10		12		12		ns

Shaded areas contain preliminary information.

Notes:

- Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified l_{OL}/l_{OH} and 30-pF load capacitance.
 t_{HZOE}, t_{HZOE}, and t_{HZWE} are specified with a load capacitance of 5 pF as in part (b) of AC Test Loads. Transition is measured ±500 mV from steady-state voltage.
 At any given temperature and voltage condition, t_{HZCE} is less than t_{LZOE}, t_{HZOE} is less than t_{LZOE}, and t_{HZWE} is less than t_{LZWE} for any given device.
 The internal write time of the memory is defined by the overlap of CE LOW, and WE LOW. CE and WE must be LOW to initiate a write, and the transition of either of these signals can terminate the write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the write.
 The minimum write cycle time for Write Cycle No. 3 (WE controlled, OE LOW) is the sum of t_{HZWE} and t_{SD}.



Switching Characteristics^[4] Over the Operating Range (continued)

		7C10	41-20	7C10		
Parameter	Description	Min.	Max.	Min.	Max.	Unit
READ CYC	LE	<u>.</u>				
t _{RC}	Read Cycle Time	20		25		ns
t _{AA}	Address to Data Valid		20		25	ns
t _{OHA}	Data Hold from Address Change	3		5		ns
t _{ACE}	CE LOW to Data Valid		20		25	ns
t _{DOE}	OE LOW to Data Valid		8		10	ns
t _{LZOE}	OE LOW to Low Z	0		0		ns
t _{HZOE}	OE HIGH to High Z ^[5, 6]		8		10	ns
t _{LZCE}	CE LOW to Low Z ^[6]	3		5		ns
t _{HZCE}	CE HIGH to High Z ^[5, 6]		8		10	ns
t _{PU}	CE LOW to Power-Up	0		0		ns
t _{PD}	CE HIGH to Power-Down		20		25	ns
t _{DBE}	Byte Enable to Data Valid		8		10	ns
t _{LZBE}	Byte Enable to Low Z	0		0		ns
t _{HZBE}	Byte Disable to High Z		8		10	ns
WRITE CYC	LE ^[7, 8]	<u>.</u>				
t _{WC}	Write Cycle Time	20		25		ns
t _{SCE}	CE LOW to Write End	13		15		ns
t _{AW}	Address Set-Up to Write End	13		15		ns
t _{HA}	Address Hold from Write End	0		0		ns
t _{SA}	Address Set-Up to Write Start	0		0		ns
t _{PWE}	WE Pulse Width	13		15		ns
t _{SD}	Data Set-Up to Write End	9		10		ns
t _{HD}	Data Hold from Write End	0		0		ns
t _{LZWE}	WE HIGH to Low Z ^[6]	3		5		ns
t _{HZWE}	WE LOW to High Z ^[5, 6]		8		10	ns
t _{BW}	Byte Enable to End of Write	13		15		ns

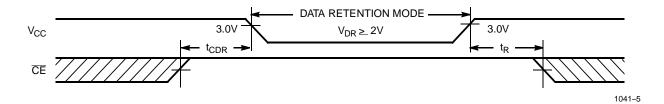
Data Retention Characteristics Over the Operating Range

Parameter	Description		Conditions ^[10]	Min.	Max.	Unit
V _{DR}	V _{CC} for Data Retention			2.0		V
I _{CCDR}	Data Retention Current		$\frac{V_{CC}}{CE} = V_{DR} = 2.0V$			μΑ
		Com'l L	$\begin{split} & \underline{V_{CC}} = V_{DR} = 2.0V, \\ & CE \ge V_{CC} - 0.3V, \\ & V_{IN} \ge V_{CC} - 0.3V \text{ or } V_{IN} \le 0.3V \end{split}$		200	μΑ
						μΑ
t _{CDR} ^[3]	Chip Deselect to Data Retention Time			0		ns
t _R ^[9]	Operation Recovery Time				See Note 9	

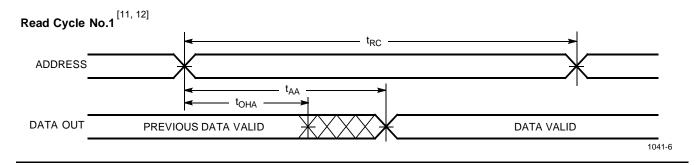
t_r≤100 μs for all speeds.
 No input may exceed V_{CC} + 0.5V.



Data Retention Waveform



Switching Waveforms



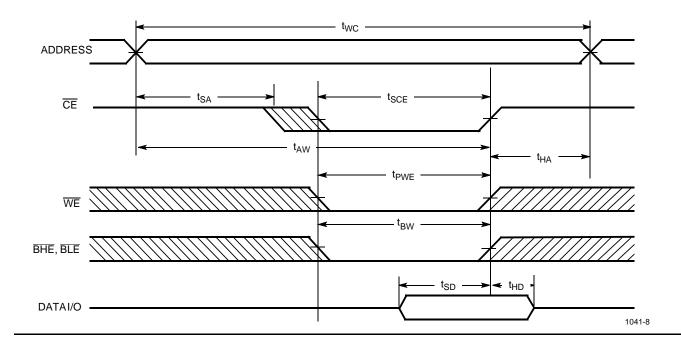
Read Cycle No.2 ($\overline{\text{OE}}$ Controlled) [12, 13] **ADDRESS** t_{RC} CE t_{ACE} ŌΕ t_{HZOE} t_{DOE} BHE, BLE t_{LZOE} → ← t_{HZCE} t_{DBE} t_{LZBE} t_{HZBE} HIGH IMPEDANCE HIGH IMPEDANCE DATA OUT -DATA VALID t_{LZCE} t_{PD} t_{PU} I_{CC} V_{CC} SUPPLY 50% CURRENT 1041-7

- 11. Device is continuously selected. \overline{OE} , \overline{CE} , \overline{BHE} , and/or $\overline{BHE} = V_{II}$.
- WE is HIGH for read cycle.
 Address valid prior to or coincident with CE transition LOW.

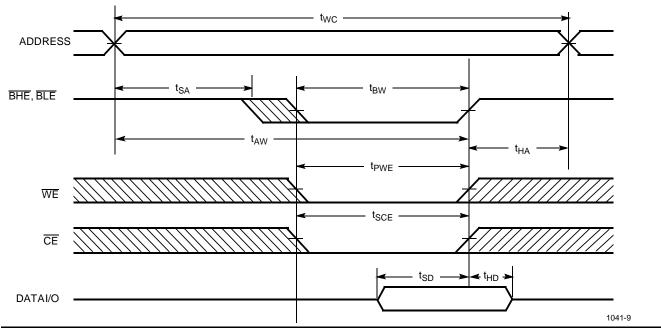


Switching Waveforms (continued)

Write Cycle No. 1 ($\overline{\text{CE}}$ Controlled) [14, 15]



Write Cycle No. 2 (BLE or BHE Controlled)



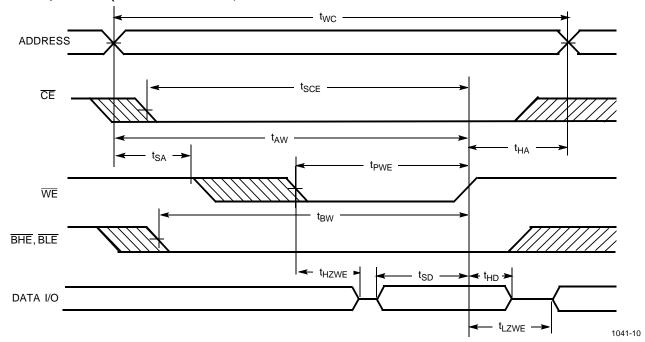
Notes:

- 14. Data I/O is high impedance if OE or BHE and/or BLE= V_{IH}.
 15. If CE goes HIGH simultaneously with WE going HIGH, the output remains in a high-impedance state.



Switching Waveforms (continued)

Write Cycle No.3 (WE Controlled, LOW)



Truth Table

CE	ΟE	WE	BLE	BHE	I/O ₀ –I/O ₇	I/O ₈ -I/O ₁₅	Mode	Power
Н	Х	Х	Х	Х	High Z	High Z	Power Down	Standby (I _{SB})
L	L	Н	L	L	Data Out	Data Out	Read All Bits	Active (I _{CC})
L	L	Н	L	Н	Data Out	High Z	Read Lower Bits Only	Active (I _{CC})
L	L	Н	Н	L	High Z	Data Out	Read Upper Bits Only	Active (I _{CC})
L	Χ	L	L	L	Data In	Data In	Write All Bits	Active (I _{CC})
L	Χ	L	L	Н	Data In	High Z	Write Lower Bits Only	Active (I _{CC})
L	Х	L	Н	L	High Z	Data In	Write Upper Bits Only	Active (I _{CC})
L	Н	Н	Χ	Х	High Z	High Z	Selected, Outputs Disabled	Active (I _{CC})



Ordering Information

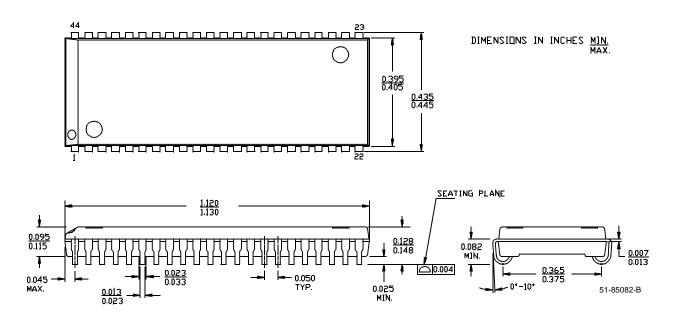
Speed (ns)	(ns) Ordering Code		Package Type	Operating Range
15	CY7C1041-15VC	V34	44-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1041L-15VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1041-15ZC	Z44	44-Lead TSOP Type II	
	CY7C1041L-15ZC	Z44	44-Lead TSOP Type II	
17	CY7C1041-17VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1041L-17VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1041-17ZC	Z44	44-Lead TSOP Type II	
	CY7C1041L-17ZC	Z44	44-Lead TSOP Type II	
20	CY7C1041-20VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1041L-20VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1041-20ZC	Z44	44-Lead TSOP Type II	
	CY7C1041L-20ZC	Z44	44-Lead TSOP Type II	
25	CY7C1041-25VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1041L-25VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1041-25ZC	Z44	44-Lead TSOP Type II	
	CY7C1041L-25ZC	Z44	44-Lead TSOP Type II	
15	CY7C1041-15ZI	Z44	44-Lead TSOP Type II	Industrial
	CY7C1041-15VI	V34	44-Lead (400-Mil) Molded SOJ	
17	CY7C1041-17ZI	V34	44-Lead TSOP Type II	
	CY7C1041-17VI	Z44	44-Lead (400-Mil) Molded SOJ	
20	CY7C1041-20ZI	Z44	44-Lead TSOP Type II	
	CY7C1041-20VI	Z44	44-Lead (400-Mil) Molded SOJ	
25	CY7C1041-25ZI	Z44	44-Lead TSOP Type II	
	CY7C1041-25VI	Z44	44-Lead (400-Mil) Molded SOJ	

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Package Diagrams

44-Lead (400-Mil) Molded SOJ V34

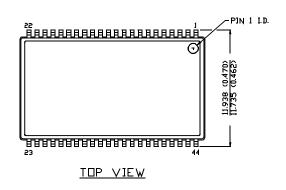


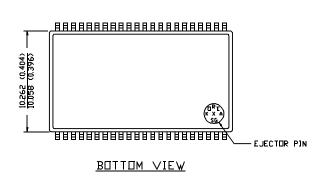
44-Pin TSOP II Z44

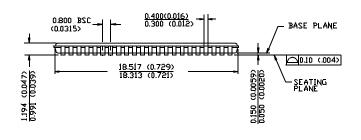
DIMENSION IN MM (INCH)

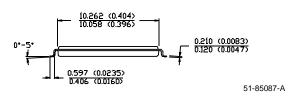
MAX

MIN.









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